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APPLICANT : APPLIED MATERIALS INC;

INVENTOR : SUNADA YOSHIHIRO;

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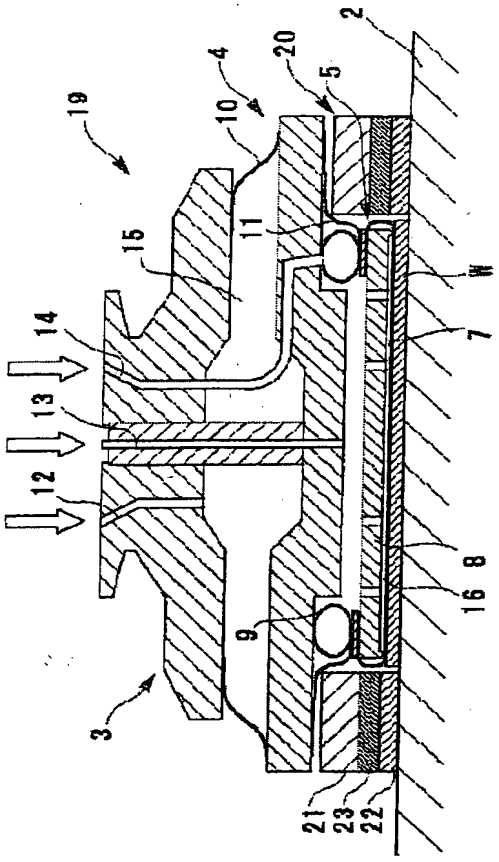
TITLE : WAFER POLISHER



ABSTRACT : PROBLEM TO BE SOLVED: To prevent the occurrence of micro-scratches on a surface of a wafer to be polished and to reduce a maintenance manhour.

SOLUTION: This wafer polisher is composed of a polishing head 13 arranged around the wafer W and incorporating a retainer ring 20 for restraining radial motion of the wafer W during polishing, an attaching plate 21 with which the retainer ring 20 is fixed to the polishing head 3, and a ceramic abrasion ring 22 mode into contact with a polishing pad 2, and a resin space 23 interposed between the attaching plate 21 and the abrasion ring 22.

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